

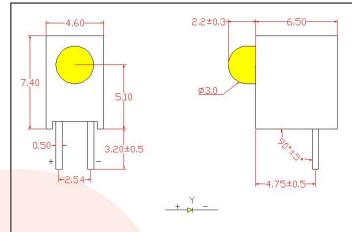
Features:

- 1. Chip material:AlInGaP
- 2. Emitted color: Yellow
- 3. Lens Appearance: Yellow Diffused
- 4. Designed for ease in circuit board assembly.
- 5. Black case enhance contrast ratio.
- 6. Solid state light source.
- 7. Reliable and rugged.
- 8. 3mm diameter package.
- This product don't contained restriction substance, compliance ROHS standard.

Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

Package dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Yellow	Unit
Power Dissipation	Pd	75	mW
Forward Current	I _F	30	mA
Peak Forward Current*1	I _{FP}	50	mA
Reverse Voltage	V _R	5	V
Operating Temperature	Topr	-40℃~85℃	
Storage Temperature	Tstg	-40℃~85℃	
Soldering Temperature	Tsol	260°C (for 5 seconds)	

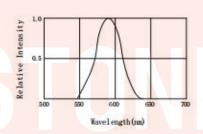
^{*1}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

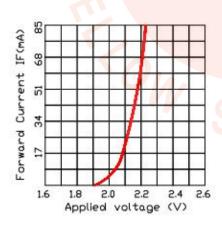


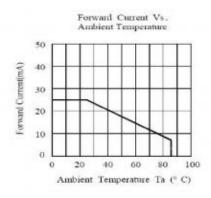
■ Electrical and optical characteristics(Ta=25°C)

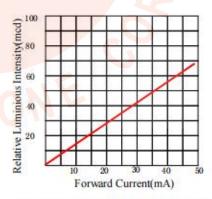
Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Forward Voltage	V _F	I _F =20mA	Yellow	1.8		2.4	V
Luminous Intensity	lv	I _F =20mA	Yellow	20		80	mcd
Reverse Current	I _R	V _R =1V	Yellow	-	-	10	μΑ
Dominant Wave Length	λd	I _F =20mA	Yellow	585	590	595	nm
Spectral Line Half-width	Δλ	I _F =20mA	Yellow	-	30	-	nm
Viewing Angle	2θ _{1/2}	I _F =20mA	Yellow	-	70		deg

Typical Electro-Optical Characteristics Curves Yellow

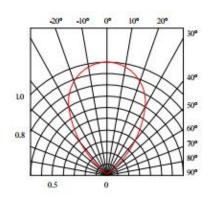








Forward Currend Vs Relative luminious Intensity

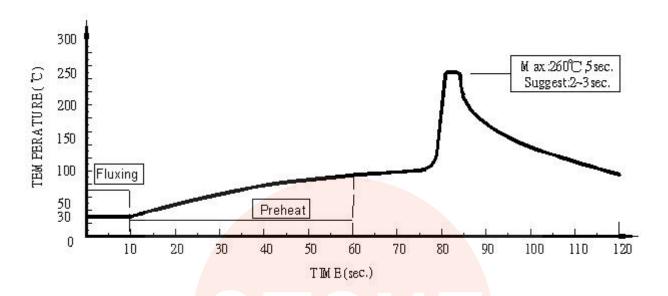


Angle distrbution

PCB



Dip Soldering



- Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- 5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C Within 2 sec. One time only

